

TM4017NF

N+P-Channel Enhancement Mode Mosfet

General Description

- Low $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

Applications

- Load switch
- PWM

General Features

N Channel

$V_{DS} = 40V$, $I_D = 20A$

$R_{DS(ON)} = 17m\Omega$ @ $V_{GS} = 10V$

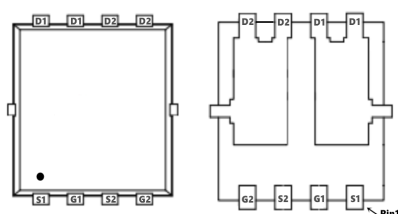
P Channel

$V_{DS} = -40V$, $I_D = -20A$

$R_{DS(ON)} = 33m\Omega$ @ $V_{GS} = -10V$

100% UIS Tested

100% R_g Tested



Marking: 20G04 OR 4020



Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max. N-Channel	Max. P-Channel	Units
V_{DSS}	Drain-Source Voltage	40	-40	V
V_{GSS}	Gate-Source Voltage	± 20	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-20	A
		$T_C = 100^\circ C$	-10	A
I_{DM}	Pulsed Drain Current ^{note1}	64	-64	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}	19	27.5	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	22	W
$R_{\theta JA}$	Thermal Resistance, Junction to Case	13	5.7	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		$^\circ C$



TM4017NF

N+P-Channel Enhancement Mode Mosfet

N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =40V, V _{GS} =0V	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =8A	-	17	24	mΩ
		V _{GS} =4.5V, I _D =5A	-	25	35	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =20V, V _{GS} =0V, f=1.0MHz	-	633	-	pF
C _{oss}	Output Capacitance		-	67	-	pF
C _{rss}	Reverse Transfer Capacitance		-	58	-	pF
Q _g	Total Gate Charge	V _{DS} =20V, I _D =8A, V _{GS} =10V	-	12	-	nC
Q _{gs}	Gate-Source Charge		-	3.2	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	3.1	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = 20V, R _L =2.5Ω V _{GS} =10V,R _{REN} =3Ω	-	4	-	ns
t _r	Turn-on Rise Time		-	3	-	ns
t _{d(off)}	Turn-off Delay Time		-	15	-	ns
t _f	Turn-off Fall Time		-	2	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	20	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	32	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = 8A	-	-	1.2	V

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=20V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=7.2A$ $T_J=25^{\circ}\text{C}, V_{DD}=-20V, V_G=-10V, L=0.5mH, R_g=25\Omega, I_{AS}=-8.4A$ 3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

TM4017NF
N+P-Channel Enhancement Mode Mosfet
P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} =0V	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-1.0	-1.5	-2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} = -10V, I _D = -8A	-	33	52	mΩ
		V _{GS} = -4.5V, I _D = -5A	-	45	70	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -20V, V _{GS} =0V, f=1.0MHz	-	1034	-	pF
C _{oss}	Output Capacitance		-	107	-	pF
C _{rss}	Reverse Transfer Capacitance		-	79.5	-	pF
Q _g	Total Gate Charge	V _{DS} = -20V, I _D = -8A, V _{GS} = -10V	-	20	-	nC
Q _{gs}	Gate-Source Charge		-	3.5	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	4.2	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -20V, I _D = -16A, V _{GS} = -10V, R _{GEN} =2.5Ω	-	8	-	ns
t _r	Turn-on Rise Time		-	15	-	ns
t _{d(off)}	Turn-off Delay Time		-	23	-	ns
t _f	Turn-off Fall Time		-	9	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-20	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-64	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -16A	-	-0.8	-1.2	V
trr	Reverse Recovery Time	V _{GS} =0V, I _S =-16A,	-	29	-	ns
Qrr	Reverse Recovery Charge	di/dt=100A/μs	-	20	-	nC



Typical Performance Characteristics-N

Figure 1: Output Characteristics

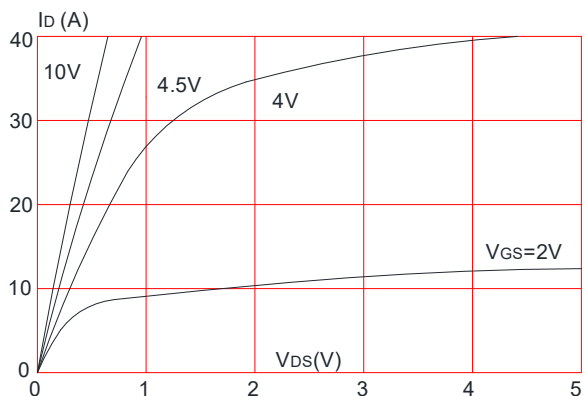


Figure 2: Typical Transfer Characteristics

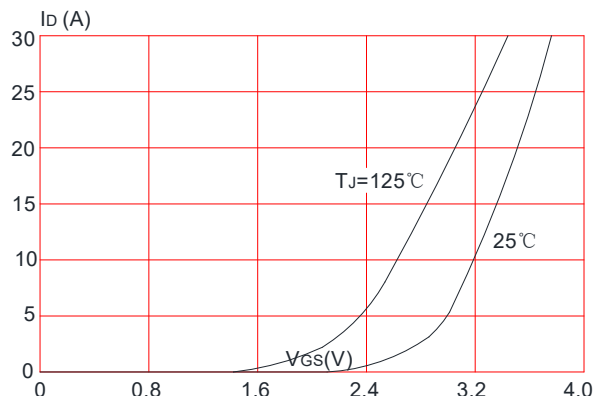


Figure 3: On-resistance vs. Drain Current

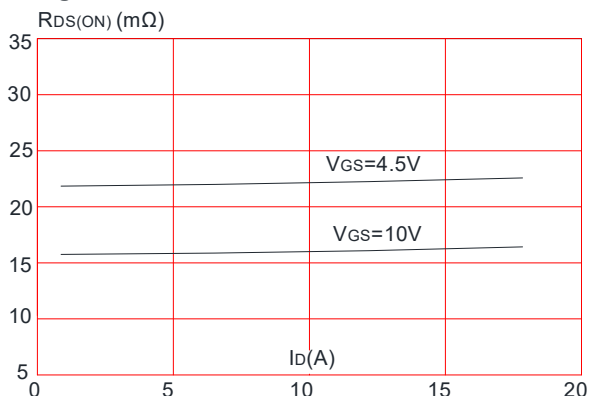


Figure 4: Body Diode Characteristics

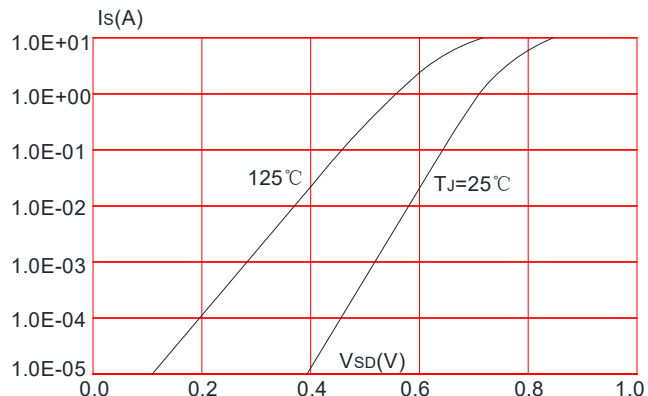


Figure 5: Gate Charge Characteristics

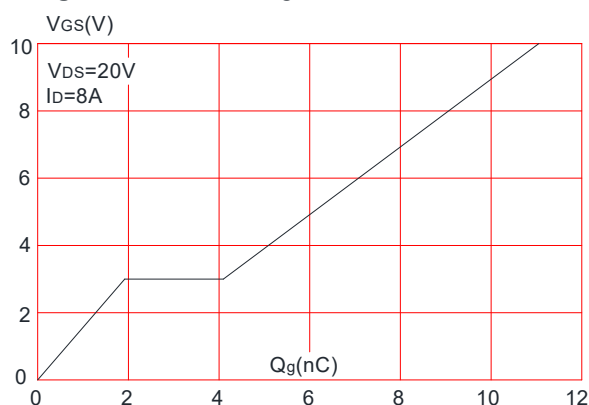
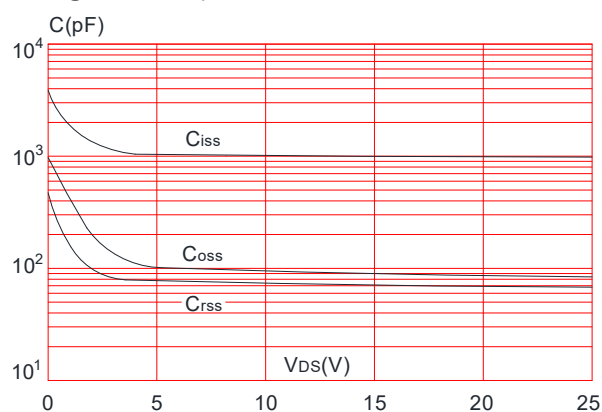


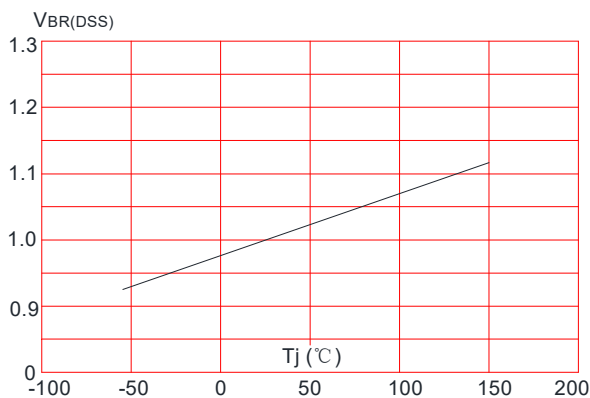
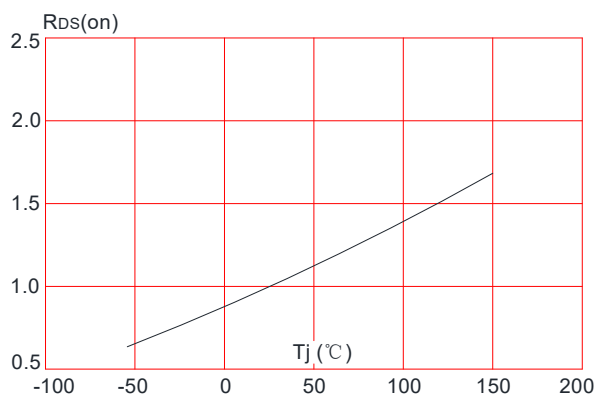
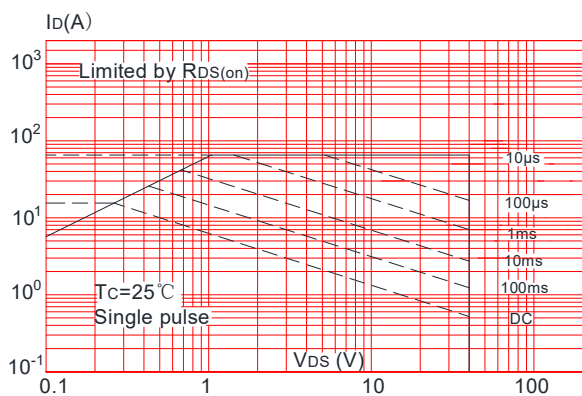
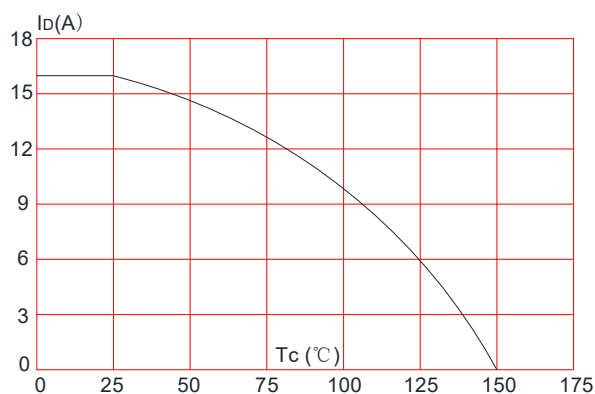
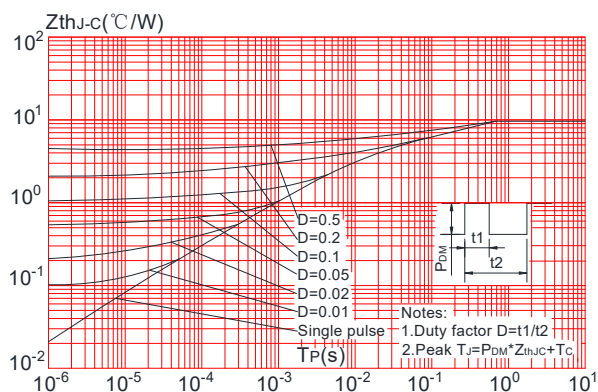
Figure 6: Capacitance Characteristics





TM4017NF

N+P-Channel Enhancement Mode Mosfet

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**Figure 8:** Normalized on Resistance vs. Junction Temperature**Figure 9:** Maximum Safe Operating Area**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature**Maximum Effective Transient Thermal Impedance, Junction-to-Case**



TM4017NF

N+P-Channel Enhancement Mode Mosfet

Typical Performance Characteristics-P

Figure 1: Output Characteristics

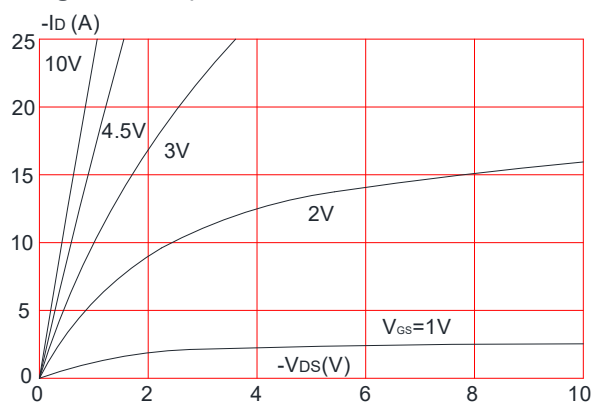


Figure 2: Typical Transfer Characteristics

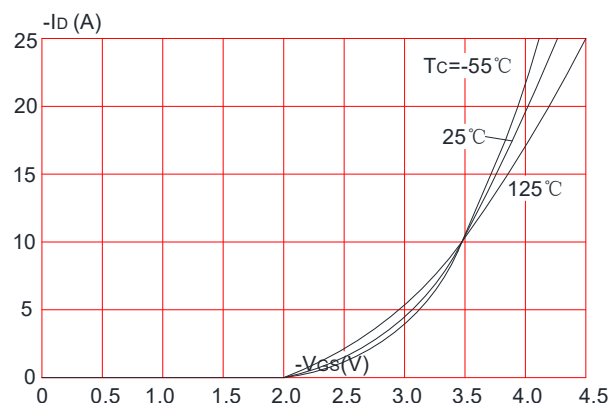


Figure 3: On-resistance vs. Drain Current

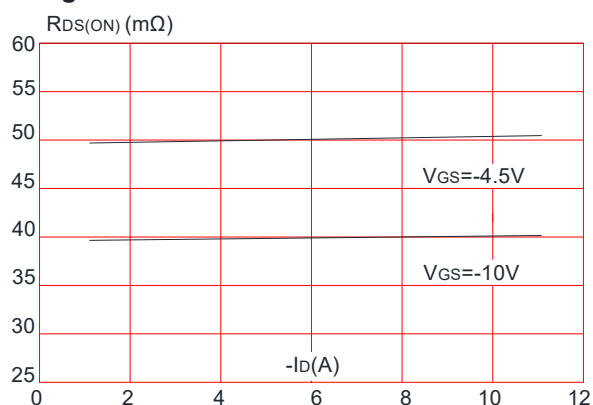


Figure 4: Body Diode Characteristics

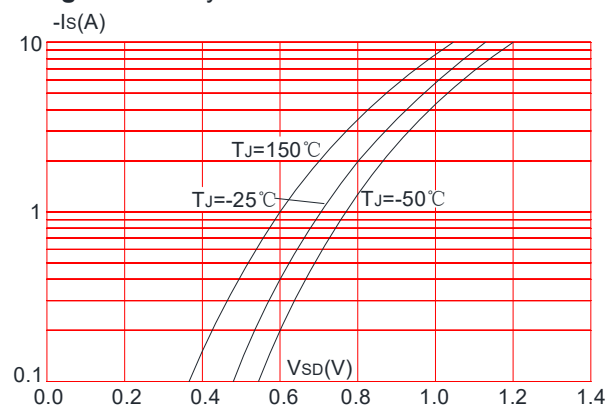


Figure 5: Gate Charge Characteristics

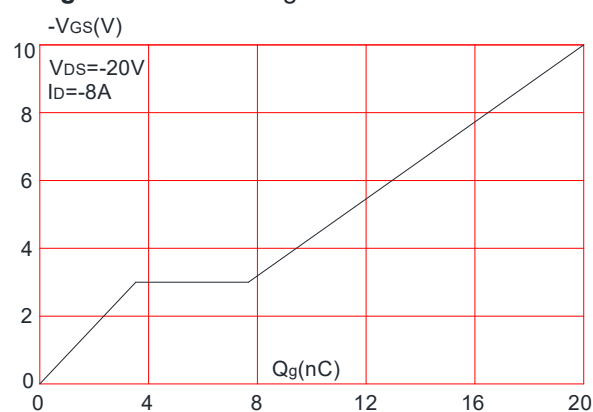
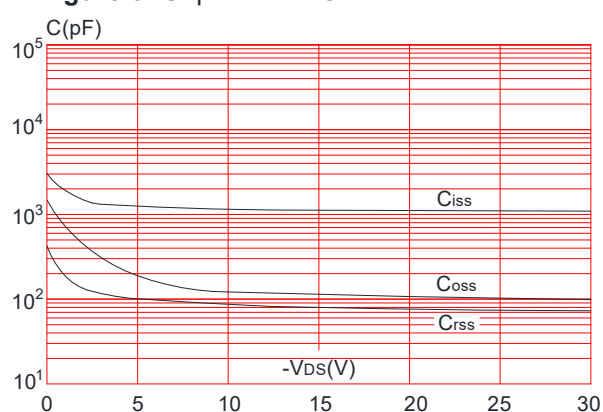


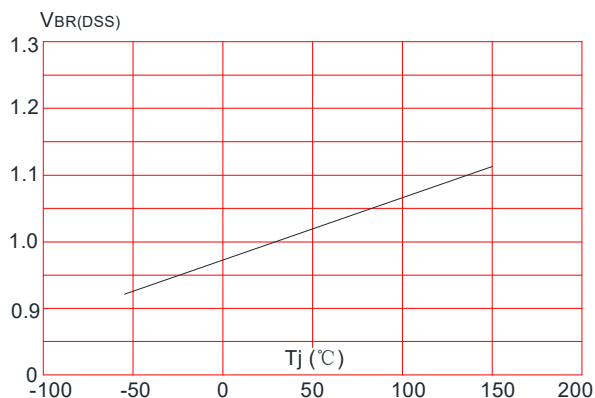
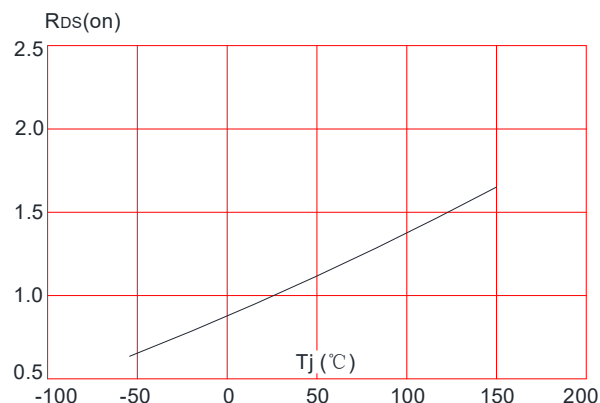
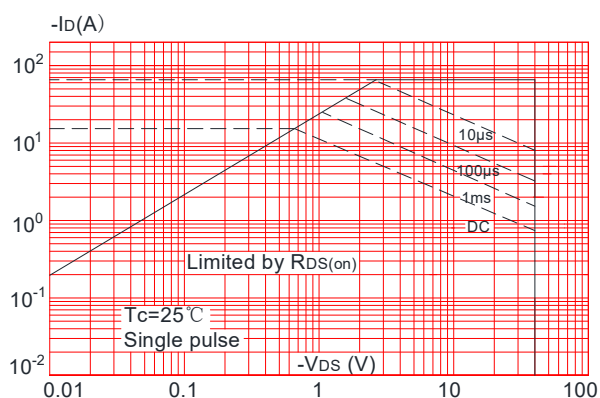
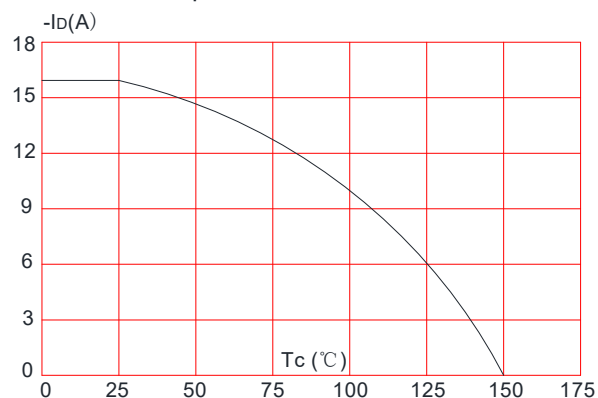
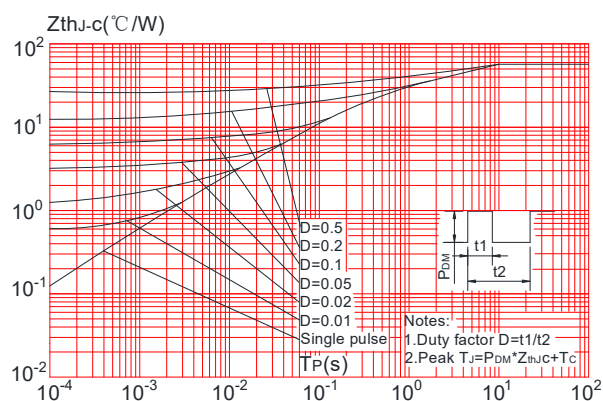
Figure 6: Capacitance Characteristics



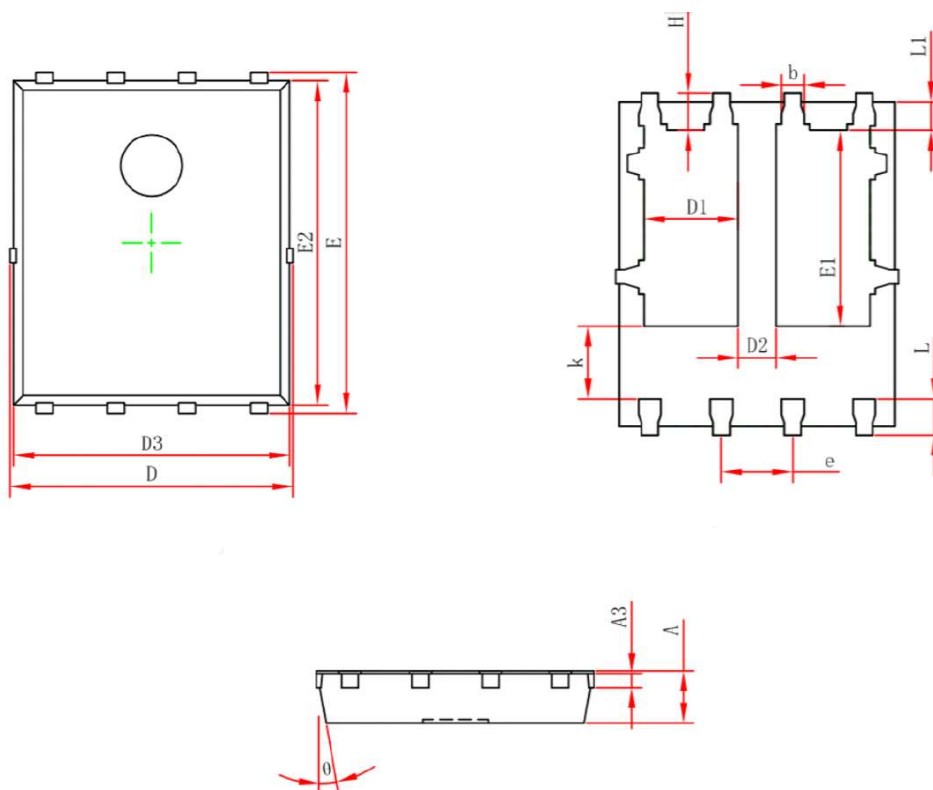


TM4017NF

N+P-Channel Enhancement Mode Mosfet

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**Figure 8:** Normalized on Resistance vs. Junction Temperature**Figure 9:** Maximum Safe Operating Area**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

Package Mechanical Data:DFN5x6-8L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.154REF.		0.006REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°